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EXAMINER

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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claim 55 is rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Pat.

No. 6,489,643 to Lee.

Regarding claim 55, Lee discloses a pixel cell for an image sensor (Fig 7 and Figure 8E), the pixel comprising:

a photodiode (Fig 7 - PPD) for generating charge in response to light and for amplifying the generated charge, the photodiode being formed within a substrate (802/801) and below and upper surface thereof and comprising at least two of a first layer (806/810 or 808/812), having a first band gap (band gap inherent to n-type or p-type material) and at least two of a second layer (808/812 or 806/810) having a second band gap (band gap inherent to p-type or n-type material), where the first layers are alternated with the second layers;

a gate (804) of a transistor (Fig 7 - transfer transistor) adjacent to the photodiode for transferring the amplified charge from the photodiode.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 1, 4, 11, 15-18 and 56 are rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Pat. No. 6,489,643 to Lee in view of U.S. Pub. No. 2002/0171077 to Chu et al. (Chu).

Regarding claim 1, Lee discloses a pixel cell for an image sensor (Fig 7 and Figure 8E), the pixel comprising:

a photodiode (Fig 7 - PPD) for generating charge in response to light and for amplifying the generated charge, the photodiode being formed within a substrate (802/801) and below and upper surface thereof and comprising at least two of a first layer (806/810 or 808/812), having a first band gap (band gap inherent to n-type or p-type material) and at least two of a second layer (808/812 or 806/810) having a second band gap (band gap inherent to p-type or n-type material), where the first layers are alternated with the second layers;

a gate (804) of a transistor (Fig 7 - transfer transistor) adjacent to the photodiode for transferring the amplified charge from the photodiode.

Lee fails to disclose a graded buffer layer beneath a bottom layer of the photodiode. Chu discloses a photodiode (Fig 2, element 22 with electrodes 11 shown in Figure 4A) and a graded buffer layer beneath a bottom layer of the photodiode (2 and 38 are graded buffer layers, paragraph [0034] and paragraph [0039]). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to have the graded buffer layer beneath a bottom layer of the photodiode as in Chu in order to improve device characteristics, such as enhancing absorption and speed of the image sensor (Chu, paragraph [0015]).

Regarding claim 4, Lee discloses the device of claim 1 and also discloses wherein at least two first layers and the at least two second layers are configured to promote ionization of a first carrier type and suppressing ionizing of a second carrier type (col 5 lines 20-30).

Regarding claim 11, Lee discloses the pixel cell of claim 1 where at least a portion of the photodiode (PPD) is at a level below a level of a top surface of the substrate (801/802).

Regarding claim 15, Lee discloses the pixel cell of claim 1, where there is a reset transistor (Fig 7 – reset transistor) for resetting the photodiode to a predetermined voltage.

Regarding claim 16, Lee discloses the pixel cell of claim 1, further comprising a floating diffusion region (Fig 7 – floating node), where the transistor (Fig 7 – transfer transistor) is a transfer transistor for transferring charge from the photodiode to the floating diffusion region.

Regarding claim 17, Lee discloses the pixel cell of claim 1 where the photodiode is part of a CMOS image sensor (col 1 lines 6-10).

Regarding claim 18, Lee discloses the pixel cell of claim 1 where the photodiode is part of a charge coupled device image sensor (col 1 lines 12-16).

Regarding claim 56, Lee discloses a pixel cell for an image sensor (Fig 7 and Figure 8E), the pixel comprising:

a photodiode (Fig 7 - PPD) for generating charge in response to light and for amplifying the generated charge, the photodiode comprising at least two of a first layer (806/810 or 808/812), having a first band gap (band gap inherent to n-type or p-type material) and at least two of a second layer (808/812 or 806/810) having a second band gap (band gap inherent to p-type or n-type material), where the first layers are alternated with the second layers;

a gate (804) of a transistor (Fig 7 - transfer transistor) adjacent to the photodiode for transferring the amplified charge from the photodiode.

Lee fails to disclose a graded buffer layer beneath a bottom layer of the photodiode. Chu discloses a photodiode (Fig 2, element 22 with electrodes 11 shown in Figure 4A) and a graded buffer layer beneath a bottom layer of the photodiode (2 and 38 are graded buffer layers, paragraph [0034] and paragraph [0039]). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to have the graded buffer layer beneath a bottom layer of the photodiode as in Chu in order to improve device characteristics, such as enhancing absorption and speed of the image sensor (Chu, paragraph [0015]).

Claim 19 is rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Pat. No. 6,489,643 to Lee in view of U.S. Pub. No. 2002/0171077 to Chu et al. (Chu) and U.S. Pat. No. 6,232,626 to Rhodes.

Regarding claim 19, Lee discloses the pixel cell of claim 1. Lee fails to disclose the substrate as silicon-on-insulator. Rhodes discloses a pixel cell where the substrate is a silicon-on-insulator substrate (col 6 lines 46-50). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to have a silicon-on-insulator substrate like Rhodes to improve device isolation between devices on the substrate.

Claims 2-3, 5-8, 12-13, 20-29 and 32-34 are rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Pat. No. 6,489,643 to Lee in view of U.S. Pub. No. 2002/0171077 to Chu et al. (Chu) and U.S. Pat. No. 5,818,322 to Tasumi.

Regarding claims 20, Lee discloses a pixel cell for an image sensor (Fig 7 and Figure 8E), the pixel comprising:

a photodiode (Fig 7 - PPD) for generating charge in response to light and for amplifying the generated charge, the photodiode being formed within a substrate (802/801) and below and upper surface thereof and comprising at least two of a first layer (806/810 or 808/812) comprising a first material (n-type or p-type material) and at least two of a second layer (808/812 or 806/810) comprising a second material (p-type or n-type material) where the first layers are alternated with the second layers;

a gate (804) of a transistor (Fig 7 - transfer transistor) adjacent to the photodiode for transferring the amplified charge from the photodiode; and

promoting ionization of a first carrier type and suppressing ionizing of a second carrier type (col 5 lines 20-30).

Lee fails to disclose the layers configured such that there is a difference between the conduction band energies of the first and second materials and a difference between the valence band energies of the first and second materials. Tasumi discloses layers of first material (silicon) and second material (SiGe) and therefore discloses the feature of a difference between the valence band energies (of the Silicon and SiGe) layers and the conduction band energies (this is inherent to the materials of Tasumi). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to have a difference between the conduction band energies of the first layer and the second materials and the valence band energies of the first and second materials as in Tasumi in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current.

Lee fails to disclose a graded buffer layer beneath a bottom layer of the photodiode. Chu discloses a photodiode (Fig 2, element 22 with electrodes 11 shown in Figure 4A) and a graded buffer layer beneath a bottom layer of the photodiode (2 and 38 are graded buffer layers, paragraph [0034] and paragraph [0039]). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to have the graded buffer layer beneath a bottom layer of the photodiode as

in Chu in order to improve device characteristics, such as enhancing absorption and speed of the image sensor (Chu, paragraph [0015]).

Regarding claims 2-3 and 5-6, Lee as modified discloses the pixel cell of claim 1 as above. Lee fails to disclose the differences of the conduction band energies of at least two first layers and the at least two second layers as greater than a difference between the valance band energies of the first and second layer (claims 2-3). Lee also fails to disclose the layers formed of a material selected from the group consisting of Si, $\text{Si}_x\text{Ge}_{1-x}$, $\text{Si}_x\text{Ge}_{1-x}\text{C}_y$, GaAs, GaAlAs, InP, InGaAs, or InGaAsP (claim 5) and where the first layer is Si and the second layer is SiGe (claim 6).

Tasumi teaches a photodiode structure (Figures 1A-1C element 2) with Si and SiGe (col 3 line 63) formed in the groove (4) of the photodiode. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to include the alternating layers of Si and SiGe as in Tasumi in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current. Additionally, the feature of a difference between the conduction band energies of the Silicon and SiGE layers as greater than a difference between the valence band energies is inherent in Lee as modified by Tasumi since the same materials (Si and SiGe) are used for the photodiode in Tasumi.

Regarding claims 21-22, Lee as modified discloses the pixel cell of claim 20 as above. Lee also fails to disclose the layers formed of a material selected from the group consisting of Si, $\text{Si}_x\text{Ge}_{1-x}$, $\text{Si}_x\text{Ge}_{1-x}\text{C}_y$, GaAs, GaAlAs, InP, InGaAs, or InGaAsP (claim 21) and where the first layer is Si and the second layer is SiGe (claim 22).

Tasumi teaches a photodiode structure (Figures 1A-1C element 2) with Si and SiGe (col 3 line 63) formed in the groove (4) of the photodiode. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to include the alternating layers of Si and SiGe as in Tasumi in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current.

Regarding claims 7-8 and 23-24, Lee as modified discloses the pixel cell of claims 6 and 22 as above. The modification of Tasumi further discloses where the layers of Si are doped to a first conductivity type and the layers of SiGe as taught by Tasumi are doped to a second conductivity type (col 5 lines 66-67 and col 6 lines 1-32).

Regarding claims 9-10 and 25-26, Lee as modified discloses the pixel cell of claims 1 and 20 as above. Lee fails to disclose where the first layer is $\text{Si}_x\text{Ge}_{1-x}$ or $\text{Si}_x\text{Ge}_{1-x}\text{C}_y$ and the second layer is $\text{Si}_y\text{Ge}_{1-y}$ or $\text{Si}_x\text{Ge}_y\text{C}_z$. Tasumi discloses the pixel cell of claim 1 where the first layer is $\text{Si}_x\text{Ge}_{1-x}$ or $\text{Si}_x\text{Ge}_{1-x}\text{C}_y$ and the second layer is $\text{Si}_y\text{Ge}_{1-y}$ or $\text{Si}_x\text{Ge}_y\text{C}_z$ (col 3 line 63). It would have been obvious to one of ordinary skill in the art at the time the invention was made to have the first layer is $\text{Si}_x\text{Ge}_{1-x}$ or $\text{Si}_x\text{Ge}_{1-x}\text{C}_y$ and the second layer is $\text{Si}_y\text{Ge}_{1-y}$ or $\text{Si}_x\text{Ge}_y\text{C}_z$ as in Tasumi in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current.

Regarding claims 12 and 27, Lee as modified discloses the pixel cell of claims 1 and 20 as above. Lee fails to disclose the photodiode comprises approximately 10 to approximately 100 layers. Tasumi discloses the photodiode comprises approximately 10

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to approximately 100 layers (Tasumi has 22 layers (Figure 1A), which falls within the claimed range). It would have been obvious to one of ordinary skill in the art at the time the invention was made to have the photodiode comprises approximately 10 to approximately 100 layers as in Tasumi in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current.

Regarding claim 13, Lee as modified discloses the pixel cell of claims 1 and 20 as above. Lee fails to disclose forming the layers of thickness of approximately 50 – 300 angstroms. Tasumi discloses forming layers of thickness of approximately 50-300 angstroms (50 angstroms, col 6 line 24). Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to use the thickness of the layers between 50 – 300 angstroms as in Tasumi in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current.

Regarding claim 28, Lee discloses the pixel cell of claim 20, where there is a reset transistor (Fig 7 – reset transistor) for resetting the photodiode to a predetermined voltage.

Regarding claim 29, Lee discloses the pixel cell of claim 20, further comprising a floating diffusion region (Fig 7 – floating node), where the transistor (Fig 7 – transfer transistor) is a transfer transistor for transferring charge from the photodiode to the floating diffusion region.

Regarding claims 32-34, Lee discloses an image sensor comprising:

an array of pixel cells (Fig 7 and Fig 8E) where at least one of the pixel cells comprises:

a photodiode (Fig 7 - PPD) formed below and upper surface of a substrate (801/802) the photodiode comprising at least two layers (806/810 or 805/808) and alternating with at least two layers (805/808 or 806/810)

and a gate (804) adjacent to the photodiode for transferring (Fig 7 - transfer transistor) the amplified charge from the photodiode.

Lee fails to disclose the two layers as Silicon and alternating with at least two layers of $\text{Si}_x\text{Ge}_{1-x}$, where x is approximately 0.5 and wherein the layers of Si are doped to a first conductivity type and wherein the layers of $\text{Si}_x\text{Ge}_{1-x}$, are doped to a second conductivity type. Tasumi teaches a photodiode structure (Figures 1A-1C element 2) with alternating layers of Si and $\text{Si}_x\text{Ge}_{1-x}$, (col 3 line 63) where x is 0.6 (col 1 line 32) which is approximately 0.5 formed in the groove (4) of the photodiode. Tasumi also teaches the layers of Si are doped to a first conductivity type and the layers of SiGe as taught by Tasumi are doped to a second conductivity type (col 5 lines 66-67 and col 6 lines 1-32). It would have been obvious to one of ordinary skill in the art at the time the invention was made to include the alternating layers of Si and $\text{Si}_x\text{Ge}_{1-x}$ as in Tasumi in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current.

Lee fails to disclose a graded buffer layer formed withing the substrate and below the photodiode. Chu discloses a photodiode (Fig 2, element 22 with electrodes 11 shown in Figure 4A) and a graded buffer layer within the substrate and below the

photodiode (2 and 38 are graded buffer layers, paragraph [0034] and paragraph [0039]). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to have the graded buffer layer beneath a bottom layer of the photodiode as in Chu in order to improve device characteristics, such as enhancing absorption and speed of the image sensor (Chu, paragraph [0015]).

Claims 30-31 and 35-37 are rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Pat. No. 6,489,643 to Lee in view of U.S. Pub. No. 2002/0171077 to Chu et al. (Chu) and U.S. Pat. No. 5,818,322 to Tasumi and U.S. Pat. No. 6,232,626 to Rhodes.

Regarding claim 30, Lee as modified discloses the image sensor of claim 20. Lee fails to disclose readout circuitry electrically connected to the floating diffusion region. Rhodes discloses readout circuitry connected to a floating diffusion region for reading out charge (col 2 lines 5-15). It would have been obvious to one of ordinary skill in the art at the time the invention was made to Lee to have readout circuitry as in Rhodes in order to allow access to image data.

Regarding claim 31, Lee as modified discloses the image sensor of claim 20. Lee fails to disclose circuitry peripheral to the array, the peripheral circuitry being at a surface of the substrate, where the substrate is silicon-on-insulator. Rhodes discloses circuitry peripheral to the array (Figure 1), the peripheral circuitry being at a surface of the substrate where the substrate is silicon-on-insulator (col 6 lines 46-50). It would

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have been obvious to one of ordinary skill in the art at the time the invention was made to Lee to have circuitry as in Rhodes in order to allow access to image data.

Regarding claim 35, Lee discloses an image sensor comprising:

an array of pixel cells (Fig 7 and Fig 8E) where at least one of the pixel cells comprises:

a photodiode (Fig 7 - PPD) formed below and upper surface of a substrate (801/802) the photodiode comprising at least two layers (806/810 or 805/808) of a first material (n-type or p-type) alternating with at least two layers (805/808 or 806/810) of a second material (p-type or n-type), and wherein the layers are configured to promote ionization of a first carrier type and suppressing ionizing of a second carrier type (col 5 lines 20-30).

and a gate (804) of a transistor (Fig 7 - transfer transistor) adjacent to the photodiode;

a floating diffusion region (Fig 7 – floating node) electrically connected to the transistor (transfer transistor)

Lee fails to disclose the two layers as selected from the group consisting of Si, $\text{Si}_x\text{Ge}_{1-x}$, $\text{Si}_x\text{Ge}_{1-x}\text{C}_y$, GaAs, GaAlAs, InP, InGaAs, and InGaAsP. Tasumi teaches a photodiode structure (Figures 1A-1C element 2) with alternating layers of Si and $\text{Si}_x\text{Ge}_{1-x}$, (col 3 line 63). It would have been obvious to one of ordinary skill in the art at the time the invention was made to include the alternating layers of Si and $\text{Si}_x\text{Ge}_{1-x}$ as in Tasumi

in order to improve device characteristics, such as enhancing absorption and speed of the image sensor and reducing dark current.

Lee fails to disclose a graded buffer layer formed withing the substrate and below the photodiode. Chu discloses a photodiode (Fig 2, element 22 with electrodes 11 shown in Figure 4A) and a graded buffer layer within the substrate and below the photodiode (2 and 38 are graded buffer layers, paragraph [0034] and paragraph [0039]). It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Lee to have the graded buffer layer beneath a bottom layer of the photodiode as in Chu in order to improve device characteristics, such as enhancing absorption and speed of the image sensor (Chu, paragraph [0015]).

Lee fails to explicitly disclose the image sensor with a processor system including a processor coupled to the image sensor and readout circuitry electrically connected to the floating diffusion region. Rhodes discloses a processor system (Fig 14) including a processor (444-CPU) coupled to the image sensor (442-CMOS IMAGER) and with readout circuitry electrically connected to the floating diffusion region (col 2 lines 5-15). It would have been obvious to one of ordinary skill in the art at the time the invention was made to Lee to have processor system as in Rhodes in order to allow access to image data.

Regarding claims 36-37, Lee as modified discloses the system of claim 35. The modification of Tasumi discloses the layers configured such that a difference between the conduction band energies of the first material (silicon) and the second materials

(SiGe) is greater than a difference between the valence band energies of the first and second materials (this is inherent to the materials of Tasumi).

Response to Arguments

Applicant's arguments filed 01/04/2008 have been fully considered but they are not persuasive.

Applicant argues (Remarks page 9 last paragraph) that Lee's elements 806 and 810 cannot be at least two of a first[/second] layer because they are connected to each other at edges thereof. Examiner disagrees, portions of elements 806 and 810 are layered and separated from one another to thus constitute two of a first[/second] layer. The claims do not specify that the layers must be entirely separate or that the layers cannot be connected at any point.

Applicant argues (Remarks page 10) that Lee's element 805 is above the substrate and only present temporarily. Examiner apologizes for the typographically error, as element 812, as shown in Fig 8E was intended to recited in the rejection (similar to element 705 as shown in Fig 7).

Applicant argues (Remarks page 11) that Lee fails to disclose the photodiode for amplifying generated charge. Examiner notes that the device of Lee has all of the structural limitations of the claimed invention the device is capable of being operated in the manner claimed by the applicant. *A claim containing a "recitation with respect to the manner in which a claimed apparatus is intended to be employed does not differentiate the claimed apparatus from a prior art apparatus" if the prior art apparatus teaches all*

the structural limitations of the claim. Ex parte Masham, 2 USPQ2d 1647 (Bd. Pat. App. & Inter. 1987). See MPEP 2114

Applicant argues (Remarks page 13-14) that Tasumi teaches away from the present application and that Lee and Tasumi are not capable of being combined. Examiner does not disagree that Tasumi discloses introducing light from a cable in a direction parallel to the wafer surface. However, examiner disagrees that Tasumi teaches away from the present invention. One of ordinary skill in the art would look to prior similar structures in determining materials for new photodiodes, such as other photodiodes, regardless of the manner of light entry. Additionally examiner notes that the direction of light entering the photodiode is not claimed.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Colleen A. Matthews whose telephone number is (571)272-1667. The examiner can normally be reached on Monday - Friday 8AM-4:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Lynne Gurley can be reached on 571-272-1670. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/C. A. M./
Examiner, Art Unit 2811

/Lynne A. Gurley/
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